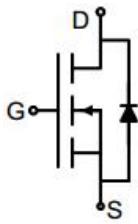
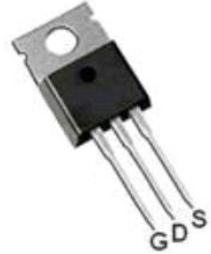


N-Channel Enhancement Mode Power MOSFET

<p>Description</p> <p>The GT100N12T uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.</p> <p>General Features</p> <ul style="list-style-type: none"> ● V_{DS} 120V ● I_D (at $V_{GS} = 10V$) 70A ● $R_{DS(ON)}$ (at $V_{GS} = 10V$) < 10mΩ ● 100% Avalanche Tested ● RoHS Compliant <p>Application</p> <ul style="list-style-type: none"> ● Power switch ● DC/DC converters 	 <p>Schematic diagram</p>  <p>TO-220</p>
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Ordering Information			
Device	Package	Marking	Packaging
GT100N12T	TO-220	GT100N12	50pcs/Tube

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted				
Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	120	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	70	A
	$T_C = 100^\circ\text{C}$		44	
Pulsed Drain Current	(note1)	I_{DM}	280	A
Gate-Source Voltage		V_{GS}	± 20	V
Power Dissipation		P_D	100	W
Single pulse avalanche energy	(note2)	E_{AS}	156	mJ
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 To 150	°C

Thermal Resistance				
Parameter		Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient		R_{thJA}	50	°C/W
Maximum Junction-to-Case		R_{thJC}	1.25	°C/W

Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	120	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 120\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	1	μA
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.0	3.0	4.0	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$	--	7.8	10	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{GS}} = 5\text{V}, I_D = 20\text{A}$	--	25	--	S
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 60\text{V}, f = 1.0\text{MHz}$	--	2990	--	pF
Output Capacitance	C_{oss}		--	335	--	
Reverse Transfer Capacitance	C_{rss}		--	4	--	
Total Gate Charge	Q_g	$V_{\text{DD}} = 60\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$	--	45	--	nC
Gate-Source Charge	Q_{gs}		--	16	--	
Gate-Drain Charge	Q_{gd}		--	11	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 60\text{V}, I_D = 20\text{A}, R_G = 1.6\Omega$	--	15	--	ns
Turn-on Rise Time	t_r		--	10	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	34	--	
Turn-off Fall Time	t_f		--	8	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	70	A
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 20\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.2	V
Reverse Recovery Charge	Q_{rr}	$I_F = 20\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = 100\text{A}/\mu\text{s}$	--	106	--	nC
Reverse Recovery Time	T_{rr}		--	60	--	ns

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.5\text{mH}$, $R_G=25\Omega$

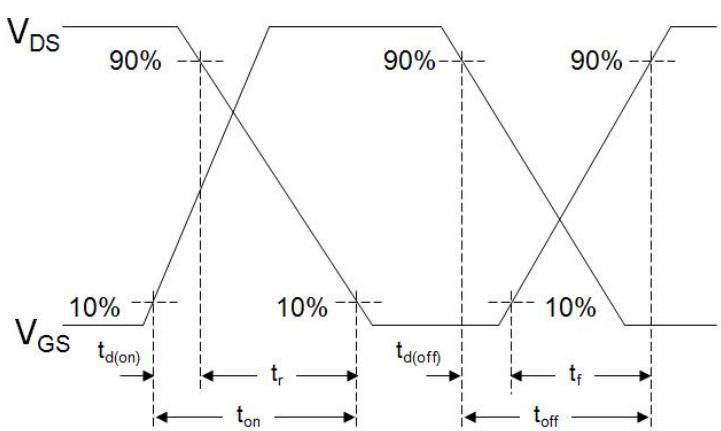
The table shows the minimum avalanche energy, which is 420mJ when the device is tested until failure

3. Identical low side and high side switch with identical R_G

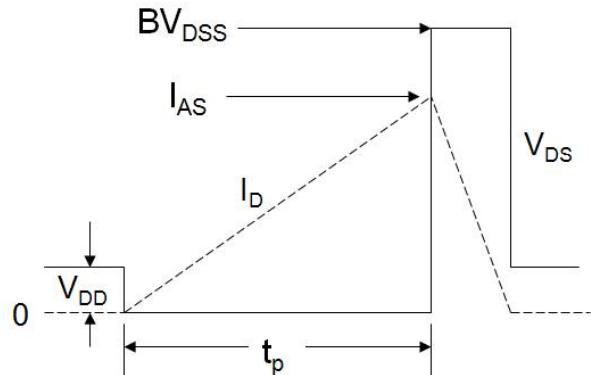
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

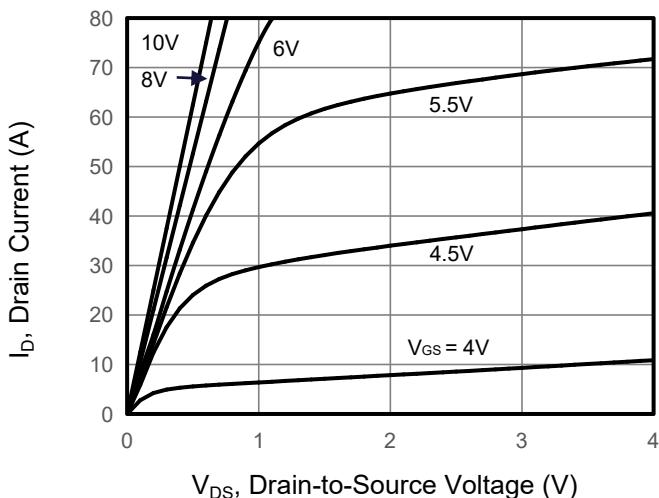


Figure 2. Transfer Characteristics

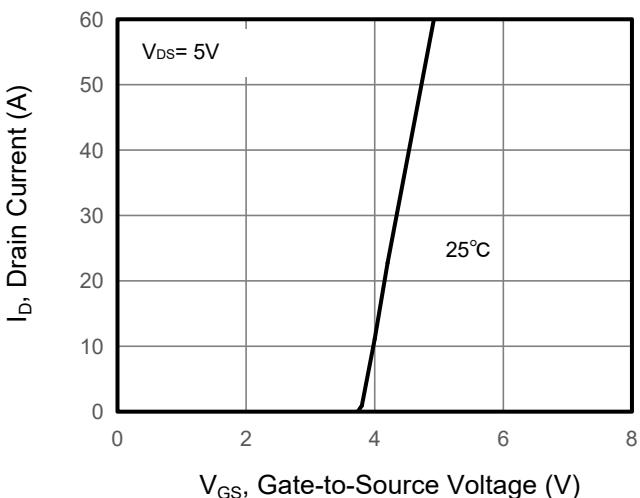


Figure 3. Drain Source On Resistance

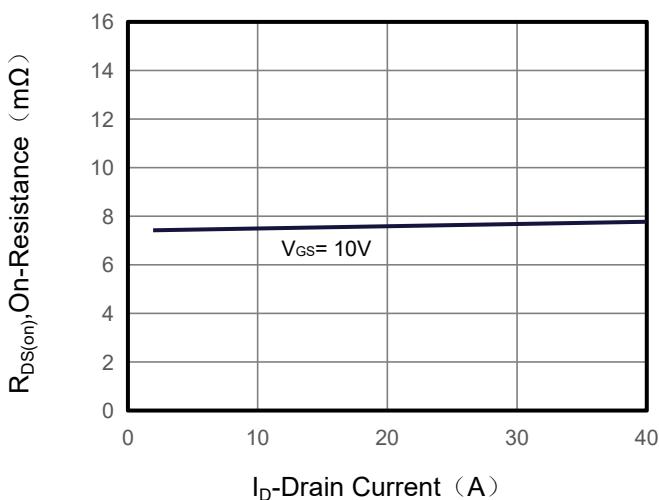


Figure 4. Gate Charge

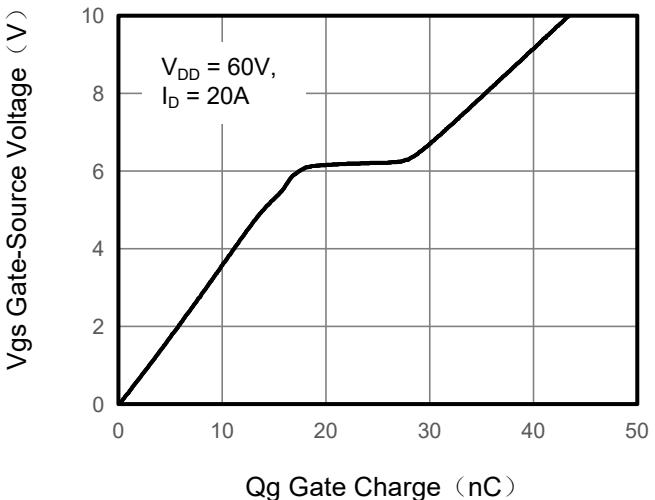


Figure 5. Capacitance

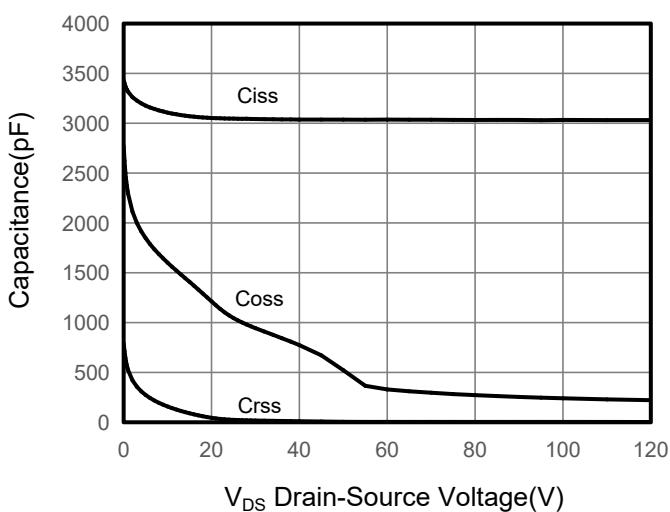
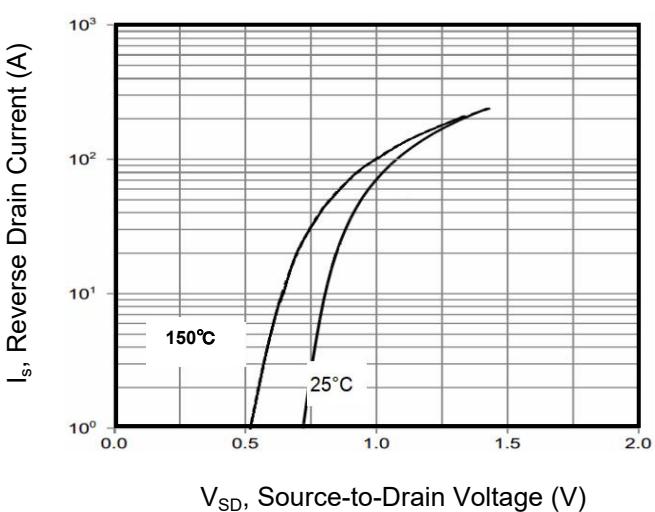


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

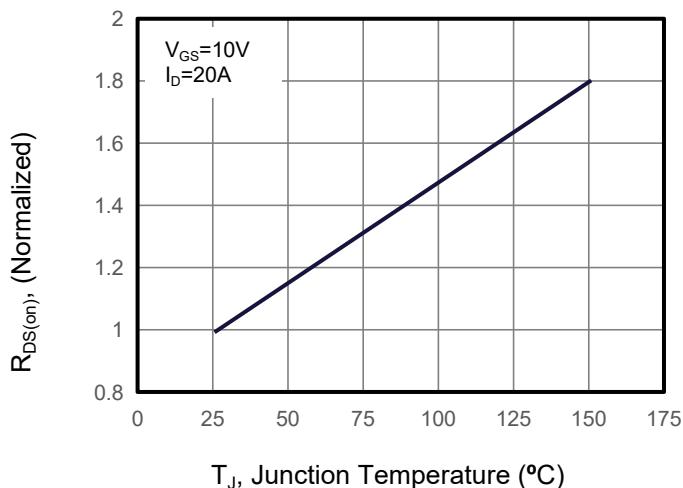


Figure 8. Safe Operation Area

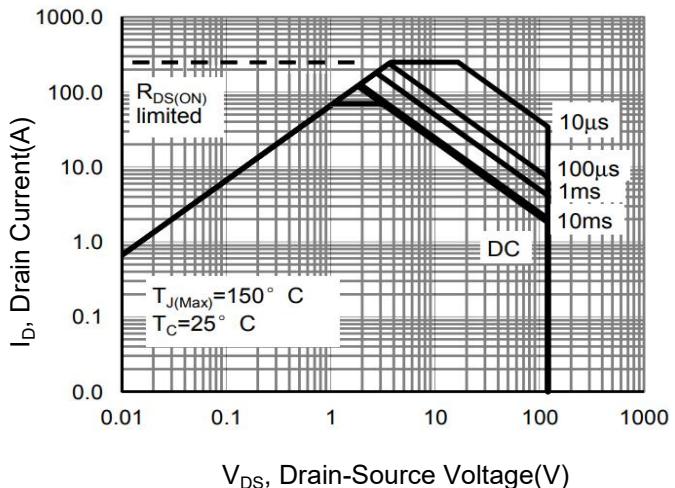


Figure 9. Maximum Continuous Drain Current vs Case Temperature

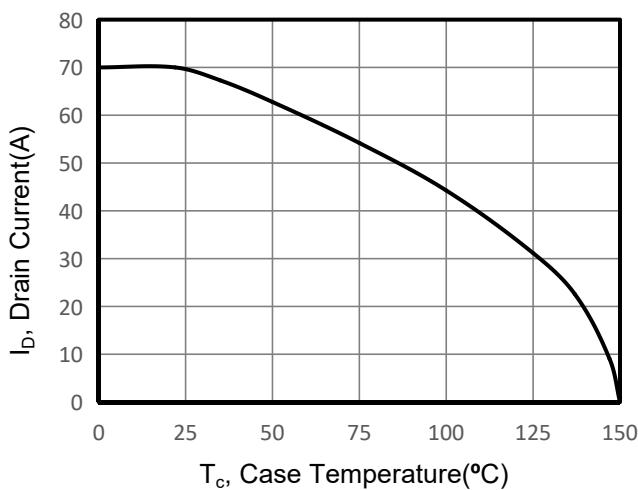
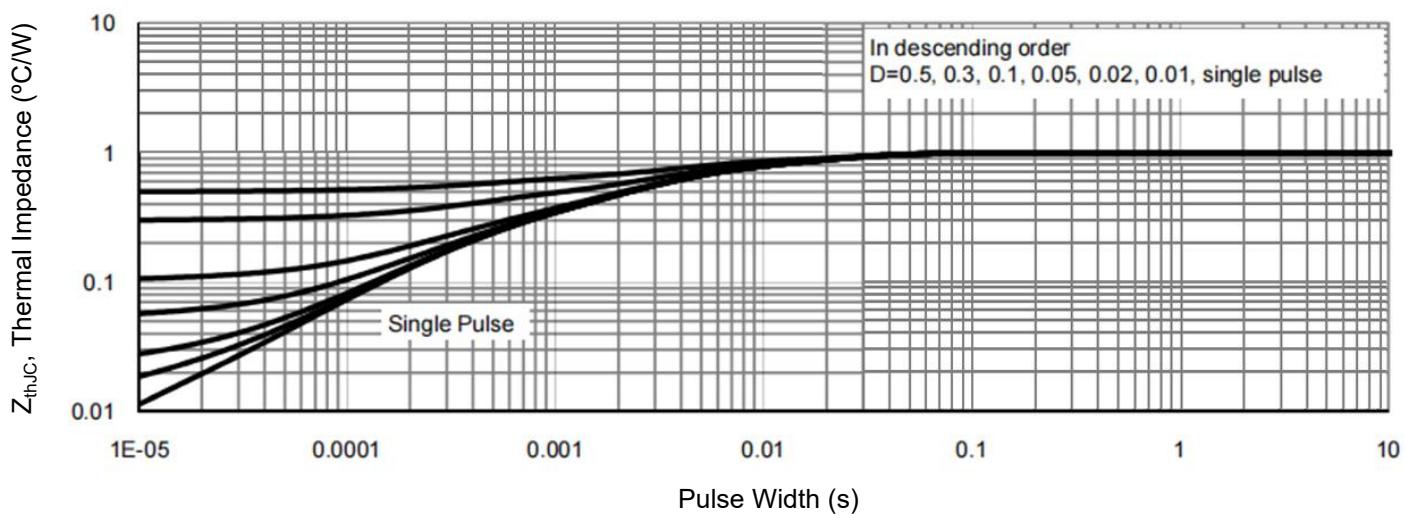
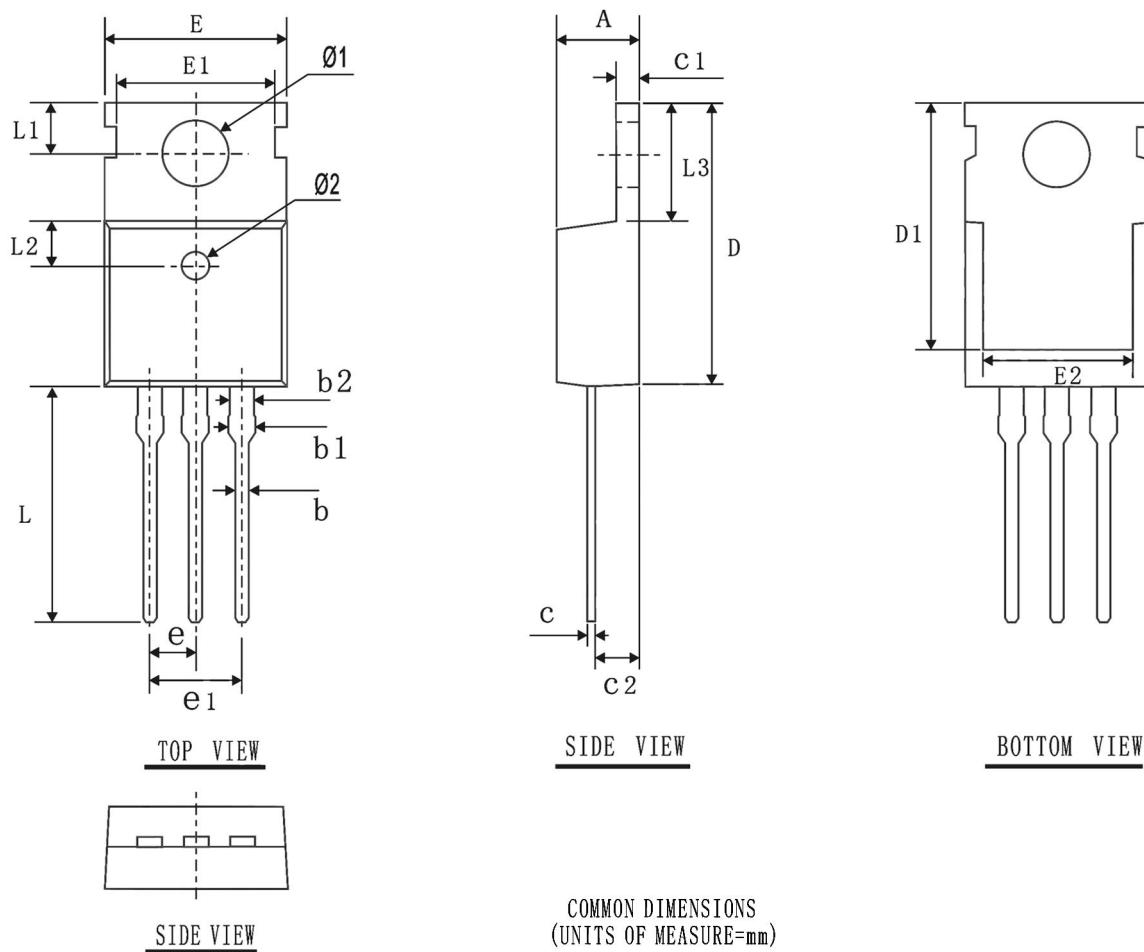


Figure 9. Normalized Maximum Transient Thermal Impedance



TO-220 Package Information



SYMBOL	MIN	NOM	MAX
A	4.30	4.50	4.70
b	0.70	0.80	0.90
b1	---	---	1.42
b2	1.17	1.27	1.37
c	0.40	0.50	0.60
C1	1.25	1.30	1.35
C2	2.20	2.40	2.60
D	15.45	15.65	15.85
D1	13.20	13.40	13.60
E	9.80	10.0	10.2
E1	8.60	8.70	8.80
E2	7.80	8.00	8.20
e1	4.88	5.08	5.28
L	12.95	13.15	13.35
L1	2.70	2.80	2.90
L2	2.40	2.50	2.60
L3	6.30	6.50	6.70
Ø1	3.50	3.60	3.70
Ø2	1.35	1.50	1.65
e	2.54BSC		